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United States Patent [19]
Dressen

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[54] **DISC PACKAGE FOR SEMICONDUCTOR WAFERS**

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[73] **Assignee: Empak, Inc., Chanhassen, Minn.**

[**] **Term: 14 Years**

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[52] **U.S. Cl. D9/424; 206/334; 206/508**

[58] **Field of Search 211/40; 206/334, 328, 206/444, 454, 455, 508; D9/337, 424, 425; D14/299**

[56] **References Cited**

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[57] **CLAIM**

The ornamental design for the disc package for semiconductor wafers, as shown and described.

DESCRIPTION

FIG. 1 is a top front perspective view of a disc package for semiconductor wafers;

FIG. 2 is a front elevational view thereof, the undisclosed rear portion is a mirror image of the front;

FIG. 3 is a top plan view thereof;

FIG. 4 is a bottom plan view thereof; and,

FIG. 5 is a side elevation view thereof, the opposite side is a mirror image of the side shown.

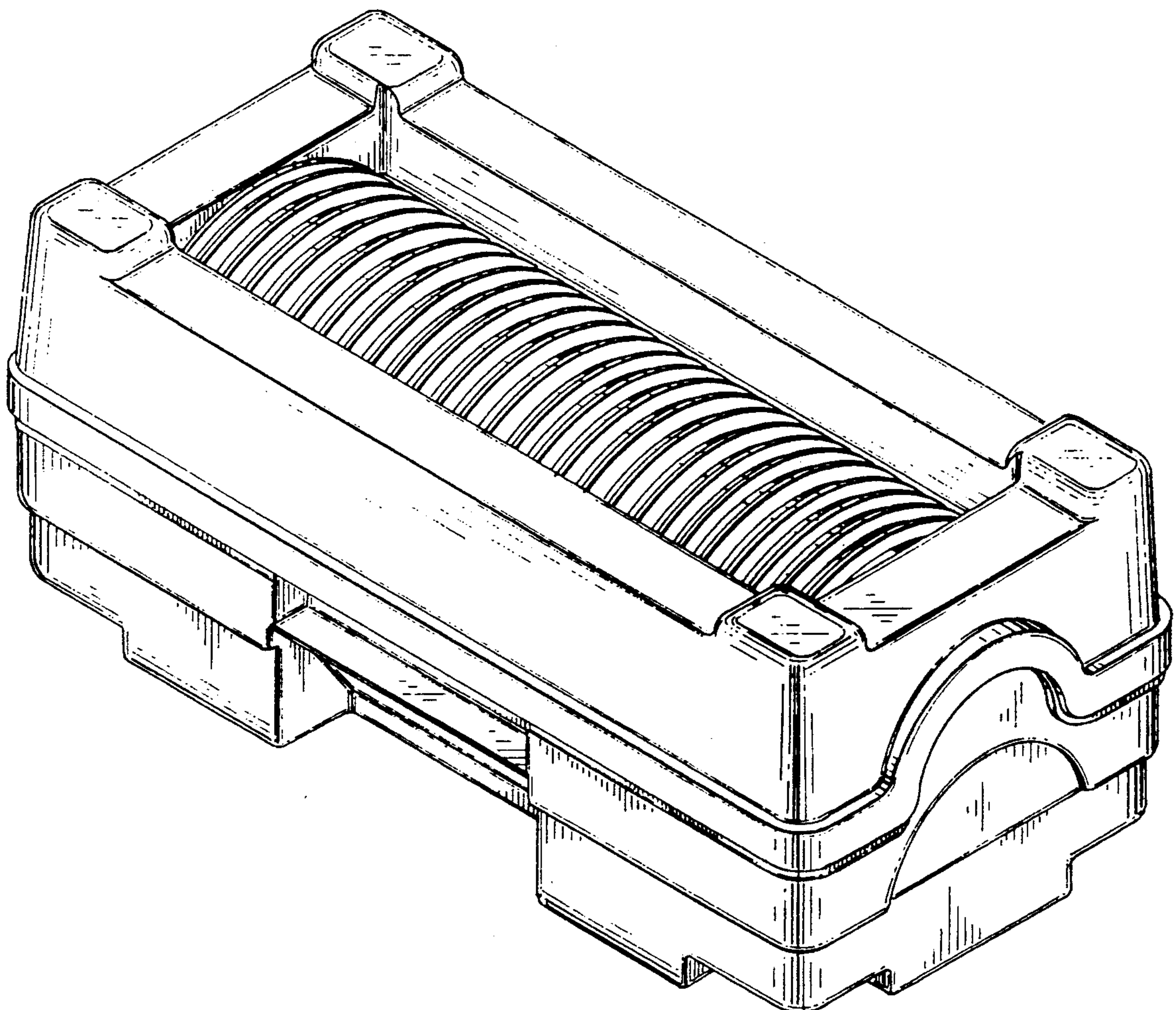


Fig.-1

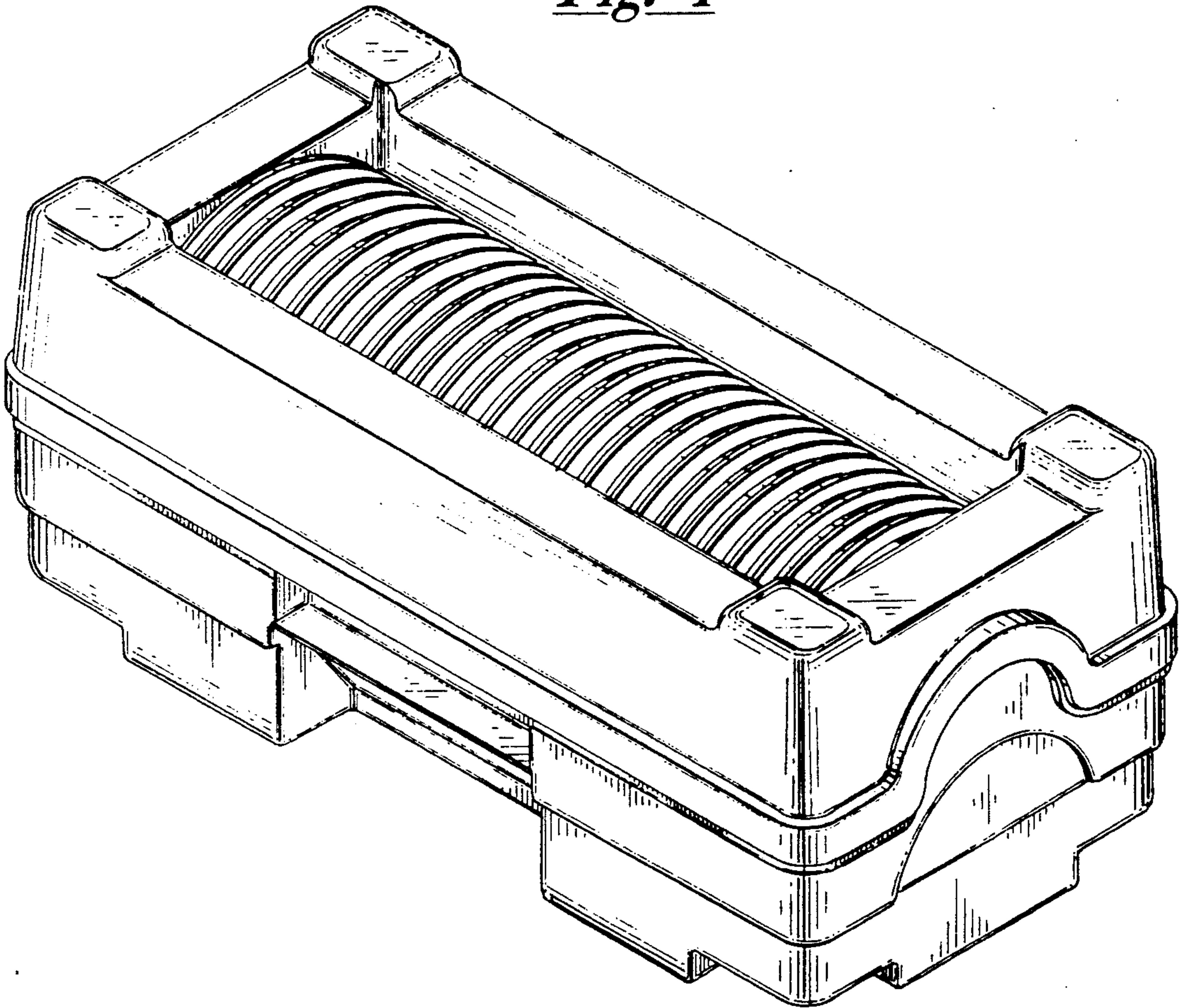


Fig.-2

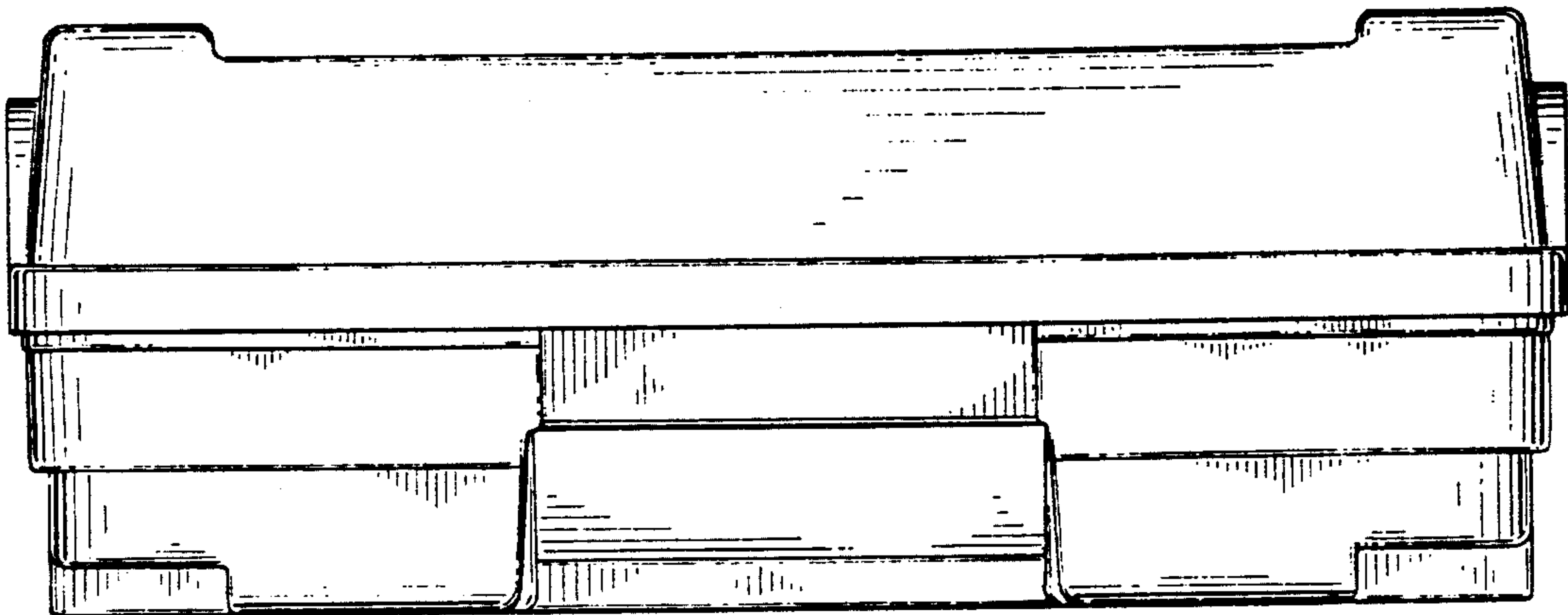


Fig.-3

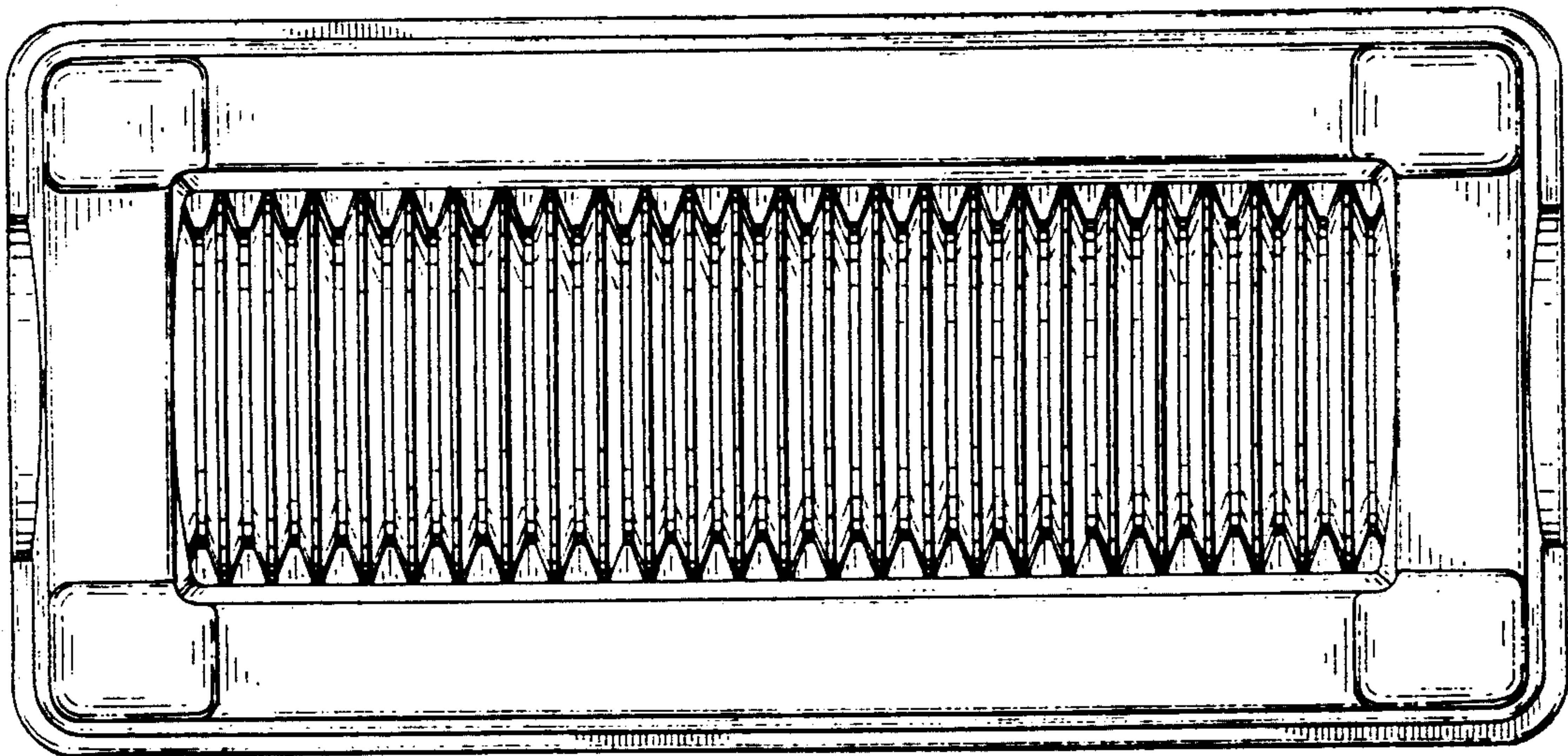


Fig.-4

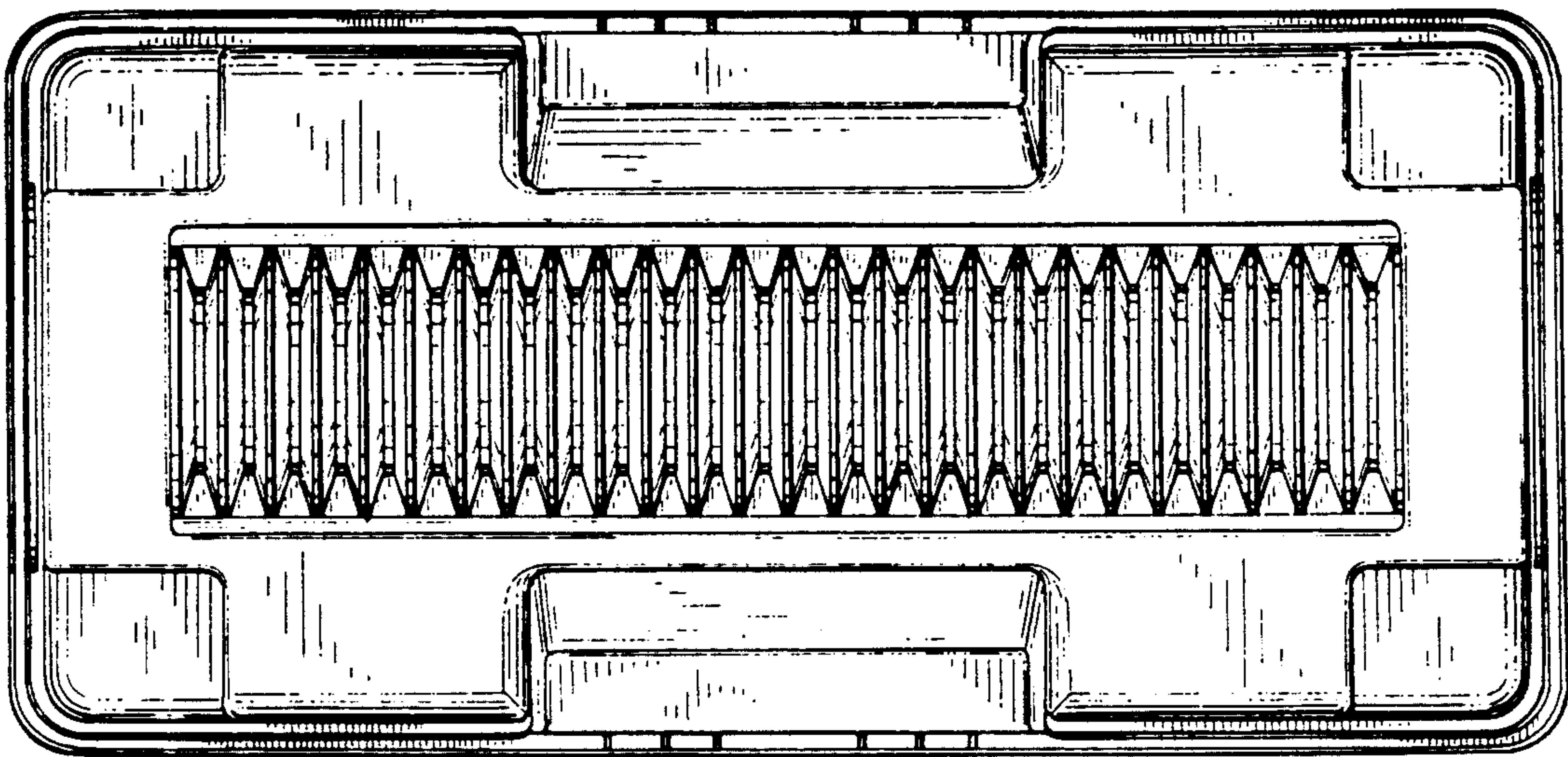


Fig.-5

